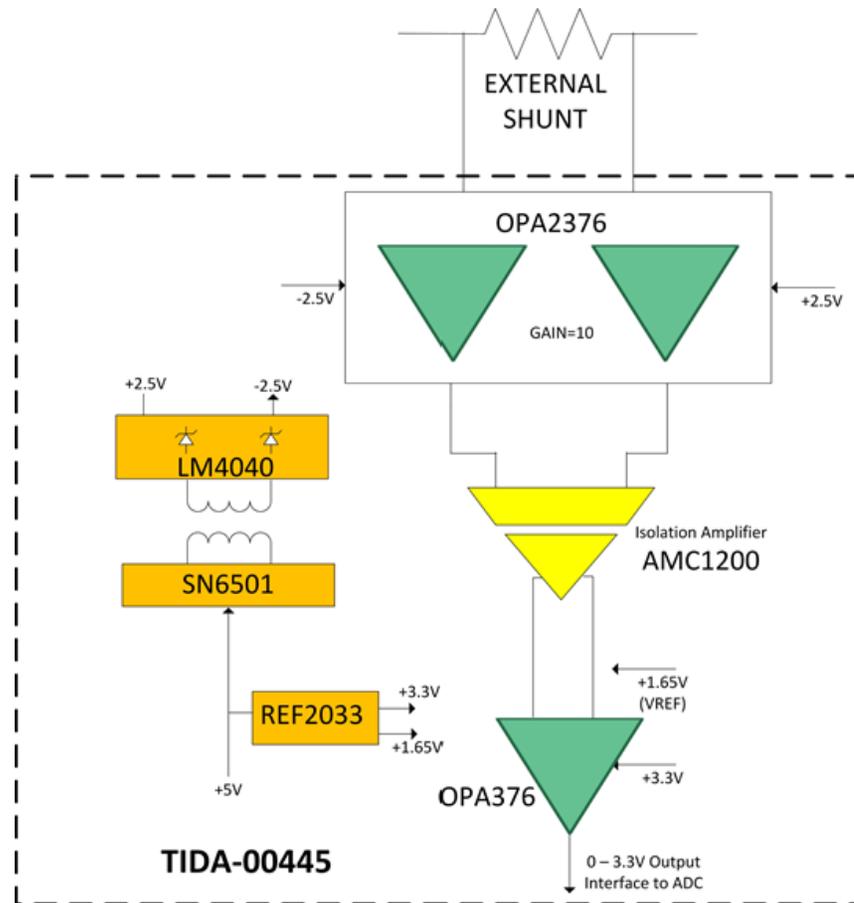
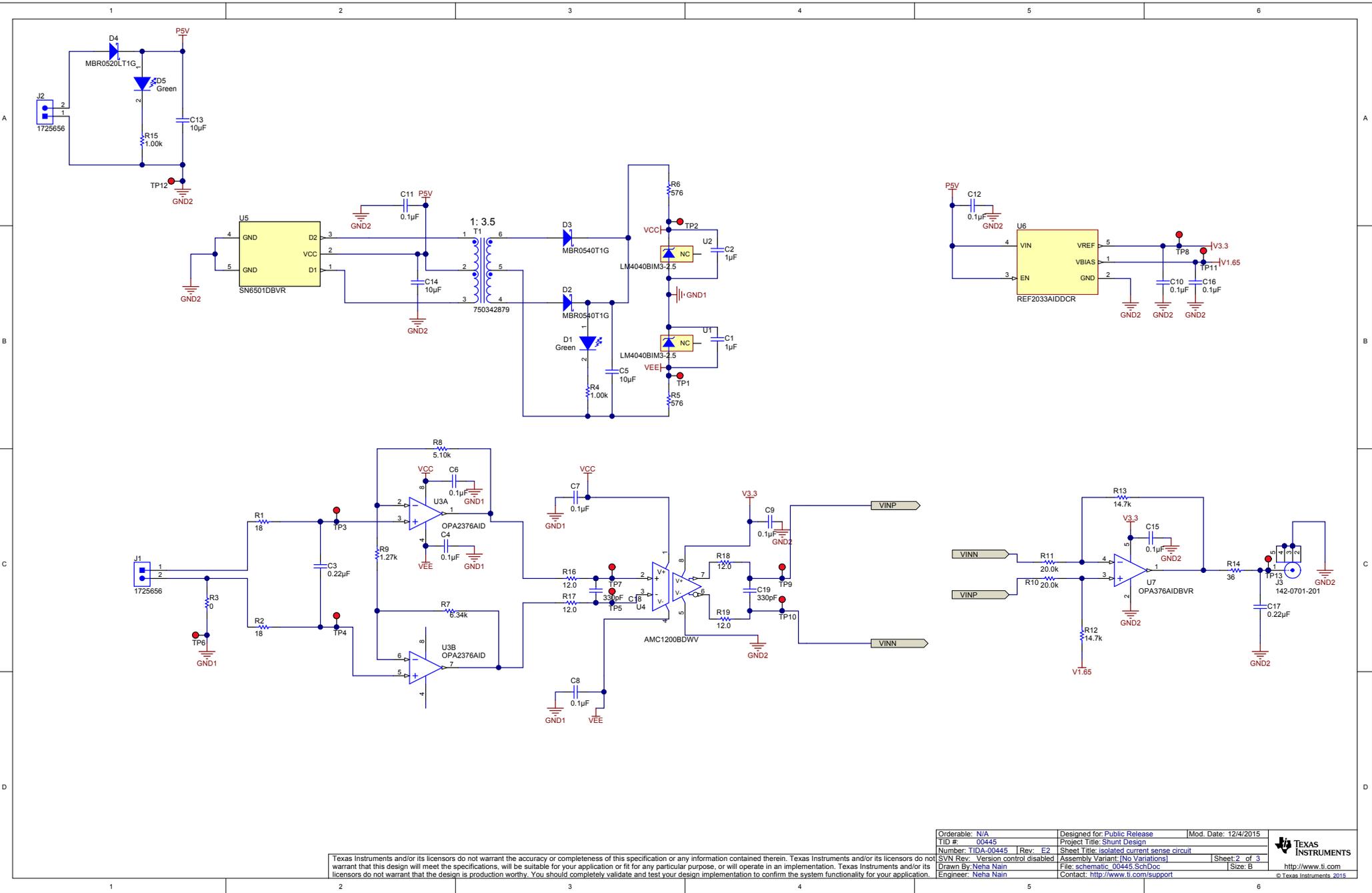


Revision History				
Rev	ECN #	Approved Date	Approved by	Notes
N/A	N/A	N/A	N/A	N/A



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Orderable: N/A	Designed for: Public Release	Mod. Date: 12/11/2015
TID #: 00445	Project Title: Shunt Design	
Number: TIDA-00445 Rev: E2	Sheet Title: Block diagram	
SVN Rev. Version control disabled	Assembly Variant: [No Variations]	Sheet: 1 of 3
Drawn By: Neha Nain	File: CoverSheet_SchDoc	Size: B
Engineer: Neha Nain	Contact: http://www.ti.com/support	



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Orderable: N/A	Designed for: Public Release	Mod. Date: 12/4/2015
TID #: 00445	Project Title: Shunt Design	
Number: TIDA-00445 Rev: E2	Sheet Title: Isolated current sense circuit	
SVN Rev: Version control disabled	Assembly Variant: [No Variations]	Sheet: 2 of 3
Drawn By: Neha Nain	File: schematic_00445_SchDoc	Size: B
Engineer: Neha Nain	Contact: http://www.ti.com/support	



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H2 1
NY PMS 440 0025 PH

H3 1
NY PMS 440 0025 PH

H1 1
NY PMS 440 0025 PH

H4 1
NY PMS 440 0025 PH

FID1

FID2

FID3

PCB Number: TIDA-00445
PCB Rev: E2

PCB
LOGO
Texas Instruments

PCB
LOGO
Pb-Free Symbol

Label Table	
Variant	Label Text
001	Prototype

ZZ1
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ2
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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Orderable: N/A	Designed for: Public Release	Mod. Date: 11/23/2015
TID #: 00445	Project Title: Shunt Design	
Number: TIDA-00445 Rev: E2	Sheet Title: Hardware components	
SVN Rev. Version control disabled	Assembly Variant: [No Variations]	Sheet: 3 of 3
Drawn By: Neha Nain	File: TID_Hardware_SchDoc	Size: B
Engineer: Neha Nain	Contact: http://www.ti.com/support	http://www.ti.com



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